

VERSION

No.	Version	Date	Details	Name	Check
1	V1.0.0	2020/4/20	Initial	wangcheng	
2	V1.0.1				

PCB Process Description	
Board Thickness	1.0mm
Base material	Copper-clad laminate
Copper Thickness	1 oz
Pad Processing	HAL&SMOBC
Solder/Mask	

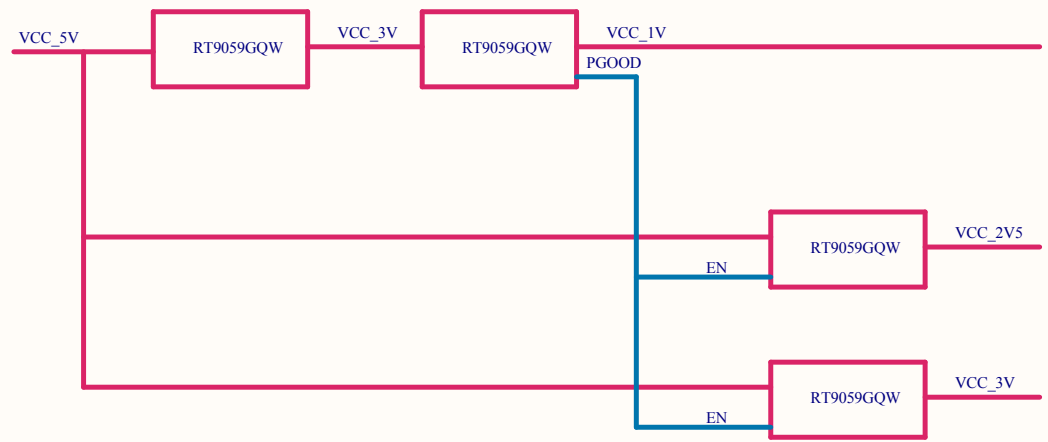
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Date:	2020/10/13	Sheet of
File:	U-work_01 VER SchDoc	Drawn By:

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B						B
C						C
D						D
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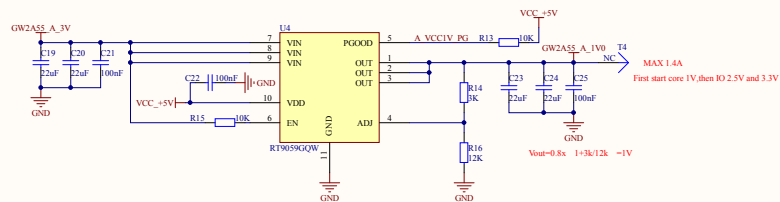
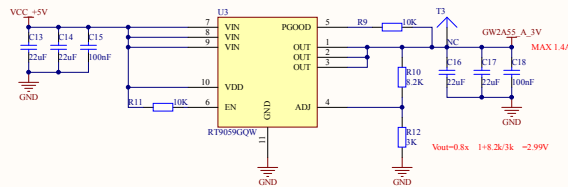
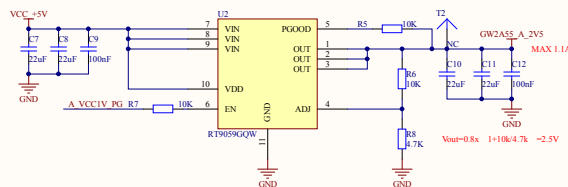
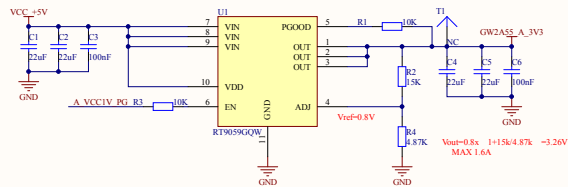
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Date:	2020/10/13	Sheet of
File:	U-work - 02 Block Diagram.SchDoc	Drawn By

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Date:	2020/10/13	Sheet of
File:	11-work - 03 Connect Explain SchDoc	Drawn By

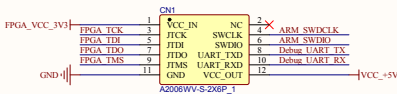
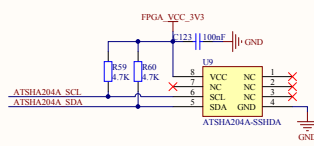
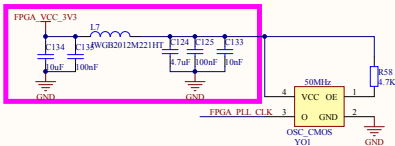
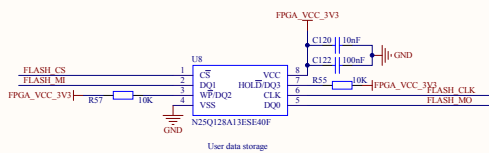
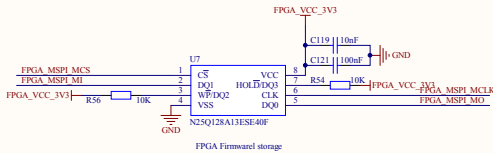
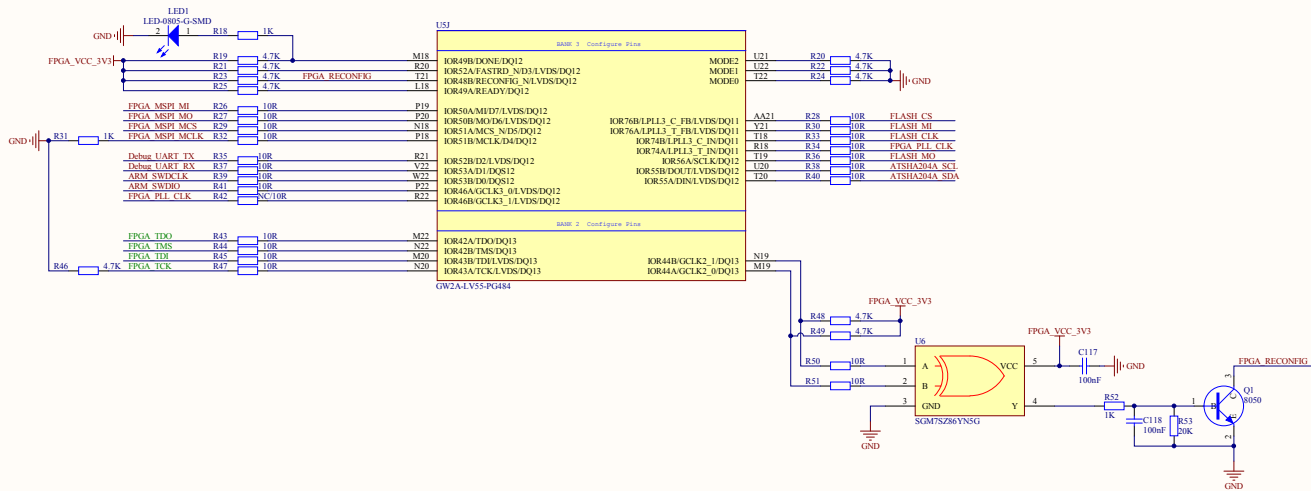


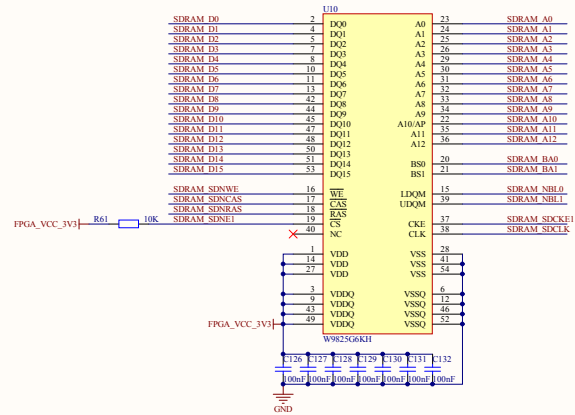
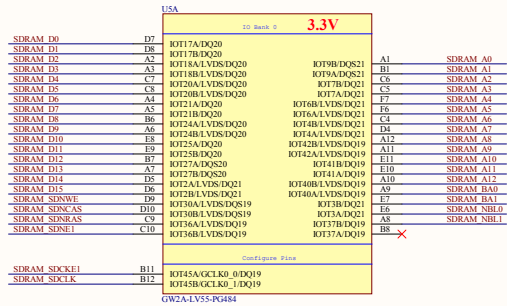
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Date:	2020/10/13	Sheet of
File:	U-work - 04 POWER TREE.SchDoc	Drawn By:

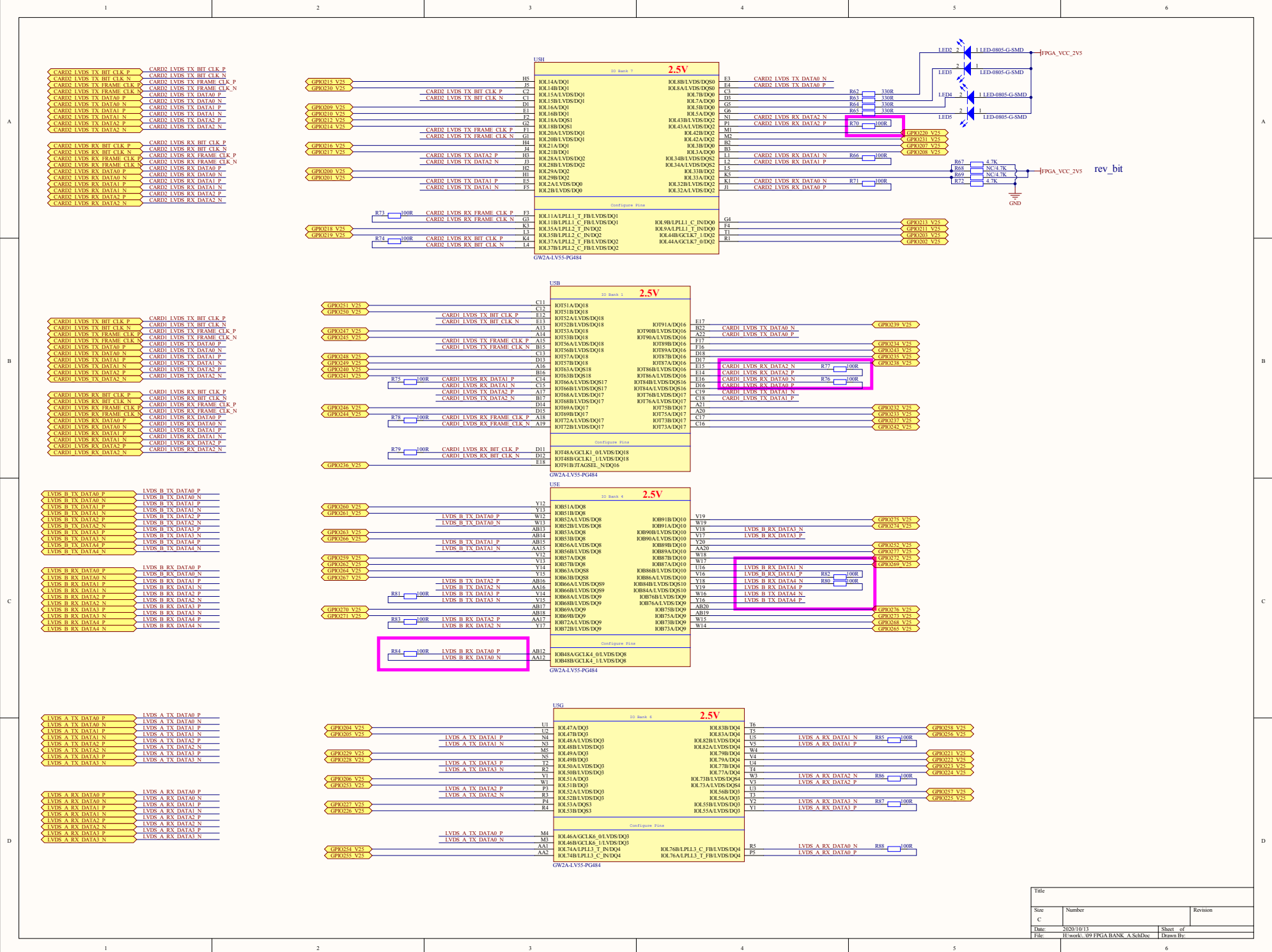


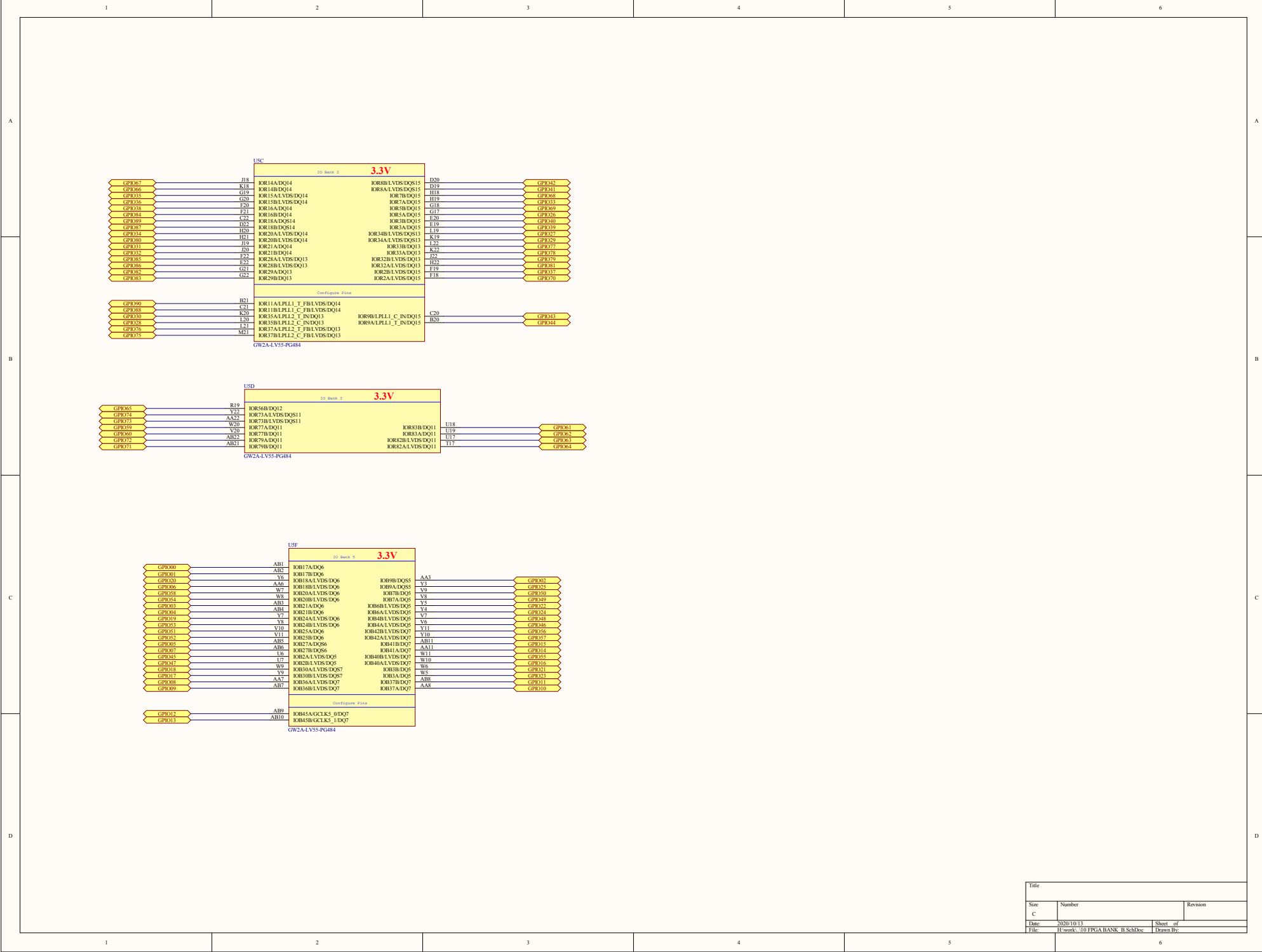
First start core 1V,then IO 2.5V and 3.3V

Title		
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File:	U-work - 05 FPGA POWER LDO Schematic	Drawn By:









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Date:	2020/10/13	Sheet of
File:	U-work-10-FPGA-BANK-B-SchDoc	Drawn By

